

**TIM-LIQUID GAP FILLERS** are thermally conductive liquid gap filler materials formulated to provide a balance of cured material properties, high lighted by “gel-like” modules and good compression set. The material is available in thermally conductive & electrically insulating or conductive, one part or two part, room or elevated temperature curing system. Form-in-place gap fillers are ideal for applying any thickness with little or no stress.



**TIM-LIQUID GAP FILLERS**

Form- in- place, Thermally Conductive Liquid Gap Fillers

**Key Features**

- High Thermal Conductivity up to 2.0 W/m<sup>o</sup>K
- Stress Absorbing Flexibility (Low Modulus) and vibration dampening
- Eliminate specific pad thickness and die-cut shapes
- Excellent mechanical and chemical stability
- Electrically Isolating and/or Conductive.
- Clean release from device/Re-workable
- No Bleed, No cure by-product, 100% solids
- Relieves CTE stresses during thermal cycling

PROPERTY	2000	2001	2002	2004
<b>AS SUPPLIED:</b>				
Viscosity cps	150,000	600,000	500,000	150,000
Mix Ratio	One Part Heat Cure	One Part RTV	One Part RTV	Two Part 1:1
Pot Life @25°C	24 hrs	8 minutes	15 minutes	1 hr
Cure time @25°C	N/A	72 Hrs	24 Hrs	2 Hrs
Cure time @120°C	30 minutes	N/A	N/A	5 minutes
Shelf life @25°C	1 year	1 year	1 year	1 years
<b>CURED PROPERTY</b> (Tested at 25°C unless otherwise indicated)				
Color	White	Gray	Gray	Pink
Density, g/cc	2.8	1.62	2.09	2.8
Hardness, shore 00/(A)	70	40(A)	40(A)	70
Thermal Conductivity, W/m <sup>o</sup> K	2.0	0.63	N/A	2.0
Dielectric Strength, Volts/mil	500	230	N/A	500
Volume Resistivity, Ohm-cm	10 <sup>12</sup>	10 <sup>15</sup>	0.09	10 <sup>12</sup>
Service Temperature, °C	-45 to 250	-65 to 260	-65 to 260	-60 to 200

**Availability:**

- 2000, 2001 & 2002: 30cc Syringe, 6 oz & 10oz Cartridge, 5 gallon pail.
- S-2004: 2 parts kit packaged in 30cc, 60cc 400cc dual cartridges. It is also available in 2 gallon & 10 gallon kits.

**Applications**

- Filling various gaps between heat generating devices to heat sinks and housings
- Automotive electronics
- Telecommunications
- Computers and peripherals
- LED bonding/Heat transfer

**Disclaimer:** All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent